



## **NEWS RELEASE**

### **FOR IMMEDIATE RELEASE**

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#### **S.E.C. announces contract to distribute Yamaha i-CUBE II**

MOORPARK, California, U.S.A., November 1, 2004—Don Moore, the president of Semiconductor Equipment Corporation (SEC) has signed a contract with Tsuneji Togami, president of IM division and director of Yamaha Motor Co., Ltd. to distribute its new i-Cube II, a high-speed automatic die mounter throughout North America and Mexico.

The i-Cube II is capable of mixed mounting SMD components and semi-conductor components as well as handling multiple types of components. It is usable for dipping and stamping by the dipping unit, and it is applicable for dispensing and for a wide area up to L300mm X W200mm.

The new i-Cube II will compliment SEC's current line of manual and semi-automatic die bonders, flipchip placement and bonding systems, laser diode bonders, eutectic die bonders, pick-and-place systems, tape applicators, die ejectors, rework stations, wafer dicing tape, UV curable and high purity tapes, and multifunctional bond testers.

Semiconductor Equipment Corporation is recognized as the leading manufacturer and distributor of standard and customized die handling equipment and semiconductor dicing tape. Since 1975, SEC has installed thousands of production units worldwide for work in packaging and assembly operations including edge emitting lasers, flipchip, surface mount, and hi-reliability devices such as ball grid arrays, quad flat packs, and multi-chip modules.